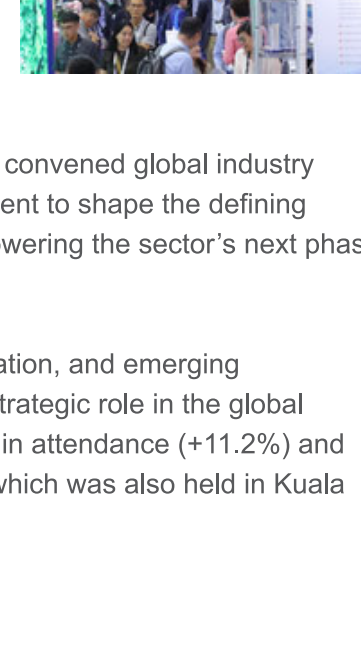


INDUSTRY CONNECT

Southeast Asia Newsletter | Q2 2026

SEMICON Southeast Asia 2026 Concludes

SEMICON Southeast Asia 2026 concluded at the Malaysia International Trade and Exhibition Centre (MITEC) with a clear signal: Southeast Asia's role in the global semiconductor value chain is evolving—moving beyond assembly, test, and packaging toward higher-value segments such as IC design and advanced packaging, and reinforcing the region's growing position as a critical hub in the ecosystem.



Held under the theme **Transform Tomorrow**, the three-day event convened global industry leaders, policymakers, manufacturers, suppliers, and emerging talent to shape the defining technologies, forge strategic partnerships, and set the priorities powering the sector's next phase of growth.

Anchored by strong industry engagement, cross-regional collaboration, and emerging technologies, SEMICON SEA 2026 further solidified the region's strategic role in the global semiconductor ecosystem and achieved record-breaking success in attendance (+11.2%) and booth participation (+26%) compared with SEMICON SEA 2024, which was also held in Kuala Lumpur.

Key Figures

21,060	65	733
Attendees	Countries/Regions	Exhibiting Companies
1,529	208	725
Booths	Speakers	Student Participation

Relive SEMICON SEA 2026 Highlights

From visionary keynotes and vibrant show floors to insightful forums and valuable networking moments — relive the highlights and connections that shaped SEMICON SEA 2026 by scanning the QR code or viewing the photo gallery [here](#).



Post Show Report

2027 Interest Form

SEMI SEA Updates

New SEMI SEA Regional Advisory Board Members

We are delighted to welcome four new members to SEMI Southeast Asia's Regional Advisory Board.

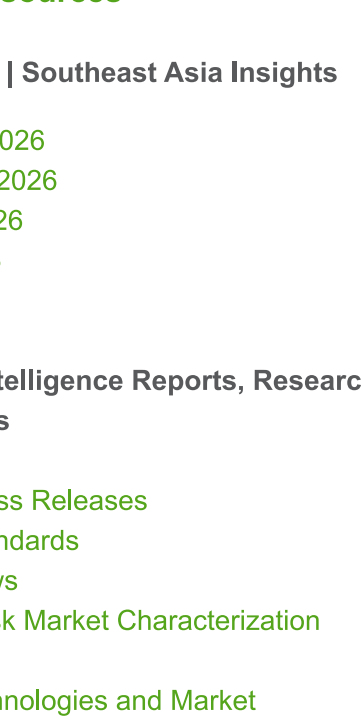
We look forward to their strategic insights and contributions as we continue strengthening Southeast Asia's role in the global semiconductor and electronics ecosystem.

Mr. Takatoshi Kyo

President

Disco Hi-Tec (Singapore) Pte Ltd

Mr. Kyo brings valuable regional leadership perspectives from DISCO HI-TEC Singapore, DISCO Corporation's Southeast Asia regional head office. With DISCO's strong expertise in precision cutting, grinding and polishing technologies, his insights will contribute to conversations around advanced manufacturing, wafer processing and the continued strengthening of Southeast Asia's semiconductor supply chain.



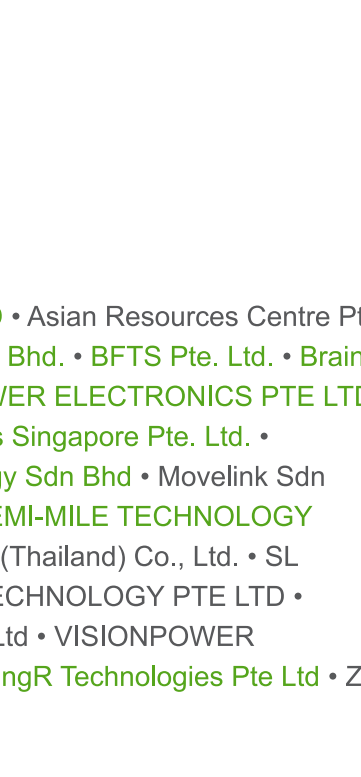
Mr. Christopher Wong

Strategy & Operations Executive SEA and General

OSAT

Lam Research

Mr. Wong brings strong leadership experience across customer operations, advanced packaging, OSAT engagement and regional semiconductor ecosystem development. His experience at Lam Research, including his leadership in customer service and advanced packaging operations, will bring valuable perspectives as Southeast Asia continues strengthening its role in next-generation semiconductor manufacturing and packaging.

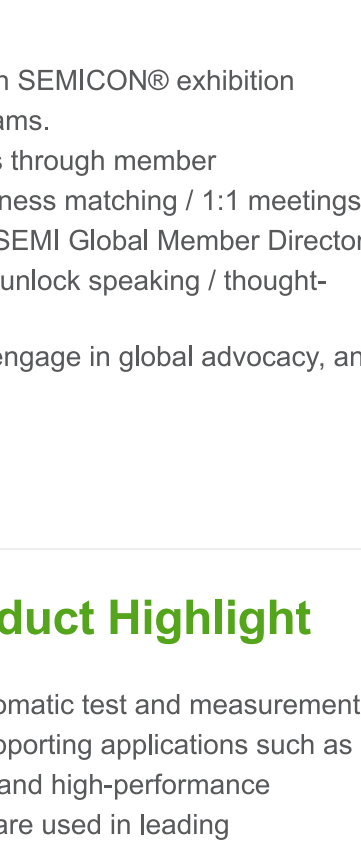


Mr. Matthew Tan

Chief Executive Officer

SiITerra

Mr. Tan brings 30 years of global semiconductor experience across Malaysia, China, the United States and Singapore, with deep expertise spanning technology, engineering, quality, customer engagement, sales and business development. As CEO of SiITerra, he plays a key role in advancing the company's strategic positioning beyond pure-play CMOS into More-than-Moore capabilities, including Silicon Photonics, Life Science and MEMS.

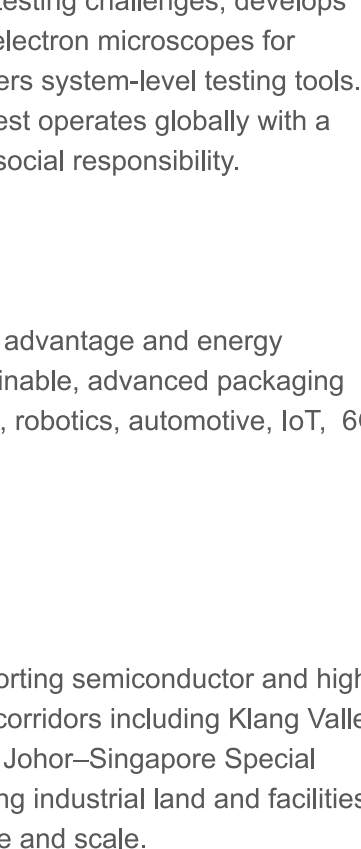


Mr. Lee Boon Chun

Site CEO

X-FAB Sarawak

Mr. Lee brings nearly 30 years of semiconductor industry experience, with deep expertise in fab operations and the foundry business. As Site CEO of X-FAB Sarawak since 2019, and through his roles with MIA, SECA and UNIMAS, he brings valuable perspectives on manufacturing leadership, industry collaboration and talent development.



SEMI SEA Membership Updates

SEMI SEA Members' Networking Breakfast

- Held during SEMICON SEA 2026 in Kuala Lumpur, the Members' Networking Breakfast brought together 113 SEMI members for a morning of meaningful connections, industry engagement, and community building.
- Highlights included the introduction of the SEMI SEA GlobalConnect Initiative, designed to help members expand internationally through SEMI's global network, pavilion programmes, and business matching opportunities.

Upcoming SEMI SEA 2026 events

- **Members' Networking Night** | 18 August, Baia (Esplanade Roof Terrace), Singapore
- **SEMIEXPO Viet Nam** | 3 – 4 December, Thishyhall Sala Convention Center, Ho Chi Minh

A Warm Welcome to our New Members

AC&C Technology Pte Ltd • **APP SYSTEMS SERVICES PTE LTD** • Asian Resources Centre Pte Ltd • **ATC Globe Holdings Pte Ltd** • **ATS Technology Services Sdn. Bhd.** • **BFTS Pte. Ltd.** • **Brain Domain Pte Ltd** • **DK Global Semiconductor Sdn Bhd** • **EDACPOWER ELECTRONICS PTE LTD** • FT-Singapore Advanced Material Pte Ltd • **Galatek Technologies Singapore Pte. Ltd.** • **HEATWISE SDN BHD** • **I-TRONICS PTE LTD** • **JF Microtechnology Sdn Bhd** • Movelink Sdn Bhd • **NOV FSG Singapore Pte Ltd** • S9FT TECH SDN. BHD. • **SEMI-MILE TECHNOLOGY PTE. LTD.** • **SineTest Technologies Pte Ltd** • Sky United Industrial (Thailand) Co., Ltd. • SL Metals Pte Ltd • SPT Asia Pte Ltd • StraitsMicro Pte. Ltd. • **TLG TECHNOLOGY PTE LTD** • TuoTuo Technology(Singapore) Pte. Ltd. • Ubot Incorporated Pte Ltd • **VISIONPOWER SEMICONDUCTOR MANUFACTURING COMPANY PTE LTD** • **XingR Technologies Pte Ltd** • Zi Lian (Malaysia) Sdn Bhd

SEMI Membership Benefits

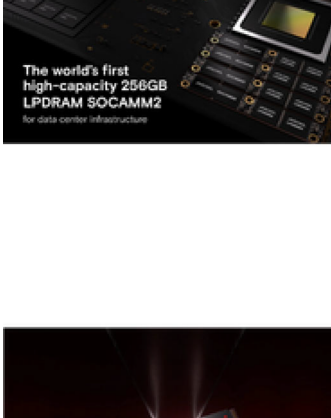
- **EMPOWER** (Save & optimise): Preferred member pricing on SEMICON® exhibition space, market intelligence & standards, and selected programs.
- **EXPAND** (Network & insight): Connect with industry leaders through member communities, committees/working groups, and curated business matching / 1:1 meetings.
- **AMPLIFY** (Visibility that converts): Be discoverable via the SEMI Global Member Directory (500K+ annual views), access new member spotlights, and unlock speaking / thought-leadership opportunities.
- **INSPIRE** (Influence & advocacy): Contribute to standards, engage in global advocacy, and help shape industry conversations and policy.

For more information, please click [here](#).

SEMICON SEA 2026 Sponsor Product Highlight



Advantest is a global leader in automatic test and measurement equipment for semiconductors, supporting applications such as 5G, IoT, autonomous vehicles, AI, and high-performance computing. Its advanced systems are used in leading semiconductor production lines worldwide. The company also conducts R&D to tackle emerging testing challenges, develops test-interface solutions, produces electron microscopes for photomask manufacturing, and offers system-level testing tools. Founded in Tokyo in 1954, Advantest operates globally with a strong focus on sustainability and social responsibility.



From Electrons to Protons

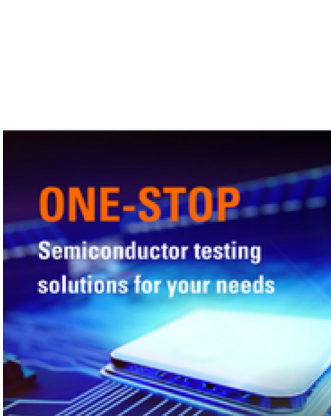
ASE is innovating for performance advantage and energy efficiency — while delivering sustainable, advanced packaging solutions for AI, HPC, data centers, robotics, automotive, IoT, 6G, aerospace, and more



EcoWorld Industrial Platform supporting semiconductor and high-tech industries across key growth corridors including Klang Valley, Malaysia Vision Valley 2.0 and the Johor–Singapore Special Economic Zone (JS-SEZ) — offering industrial land and facilities for businesses to establish, operate and scale.



We deliver **TAILORED INDUSTRIAL SOLUTIONS** — Land Sale, Built-to-Suit (BTS), Built-to-Lease (BTL), Data Centre, Ready-built Industrial Factory and One-Stop Project Management — enabling efficient setup, seamless operations and scalable growth within a future-ready environment. Contact us to explore opportunities <https://ecoworld.my/industrialplatform/>



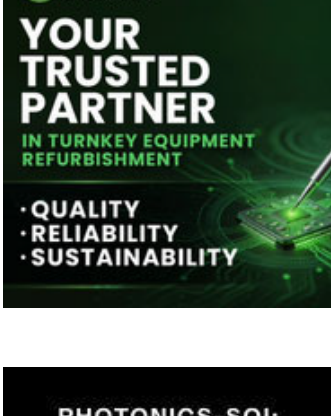
Henkel delivers advanced electronics materials for wire bonding and advanced packaging, supporting high-performance applications across AI/HPC, data centers, automotive, and consumer devices. Our portfolio addresses the reliability, performance, and manufacturability challenges in today's demanding semiconductor environments. Backed by strong innovation capabilities and regional application engineering (AE) support, we partner with customers from material selection to process optimization - enabling scalable, future-ready packaging solutions that power next-generation electronics.



Founded in 1994, IAQ Group is a Malaysia-based Total Facility Solutions Provider with over 30 years of expertise in delivering high-performance facilities for the semiconductor and advanced manufacturing industries.



With capabilities across EPCC, EPCM, energy facility management, and process-critical utilities, IAQ provides end-to-end solutions from design and construction to commissioning, optimisation, and total tool installation. Our portfolio includes semiconductor wafer fabrication plants, district cooling systems, and industrial infrastructure.



IAQ is committed to delivering mission-critical environments with the highest standards of quality, safety, and technical excellence.



KLA develops industry-leading equipment and services that enable innovation throughout the semiconductor industry. KLA provides advanced process control and process-enabling solutions for manufacturing wafers and reticles, integrated circuits, advanced packaging and printed circuit boards.



Recent innovations in semiconductor manufacturing, particularly in advanced packaging, have enabled complex integrated chips used for AI and other high performance applications, but added complexity requires a greater degree of process control to maintain high yields, driving the need for KLA's critical solutions.

For more information, please click [here](#).



Lam Research's advanced packaging portfolio enables more powerful AI accelerators to

- Overcome the memory wall
- Support increased I/O count
- Allow for more energy-efficient computing

—all while maintaining reliability and yield essential for commercial success.

Our advanced packaging solutions deliver superior technical performance across all critical parameters: uniformity, yield, process control, and throughput. With industry-leading metrology integration and process capabilities, Lam tools provide the precision and reliability required for today's most challenging packaging applications.

For more information, please visit [Packaging Solutions | Our Solutions | Lam Research](#).



Micron SOCAMM2 is the first to market with a data center class modular form factor for LPDDR5X and is designed to be the flagship memory solution for AI data centers. Low-power DRAM, paired with Compression Attached Memory Module (CAMP), offers superior performance and power efficiency in a revolutionary new form factor, saving space over traditional DDR5 RDIMM configurations.

Powered by next-generation NVMe technology, the SANDISK Optimus™ GX PRO SSD is purpose-built for ultra-high-performance computing, gaming, and data-intensive workloads. Engineered on advanced PCIe Gen 4.0 and Gen 5.0 platforms, it delivers exceptional read and write speeds, low latency, and superior reliability. Designed to meet the demands of creators, AI applications, and high-volume data processing, the GX Pro ensures seamless multitasking and accelerated workflows. With scalable capacities and enhanced thermal management, it provides consistent peak performance for modern systems.

For more information, please visit <https://www.sandisk.com/>.

Reinforcing Semiconductor Reliability through IoT Driven Innovation

Schneider Electric's EcoStruxure™ solutions are transforming semiconductor fabs with smarter operations, greater efficiency, and stronger sustainability.

Through IoT-driven technologies, fabs can enhance facility management, reduce energy use, improve asset reliability, and accelerate time to production.

Learn more: <https://www.se.com/ww/en/work/solutions/semiconductor/>

Your ONE-STOP semiconductor testing solutions for your needs. We help you to successfully access target markets with safe, compliant and cyber secure products, enabling risk mitigation and helping your products stand out.

Our services include:

- Functional Safety & Reliability
 - Cybersecurity & Digital Trust
 - EMC & Wireless Testing
 - Product & Machinery Safety
- By integrating with the SGS global network, we offer a wealth of experience in functional safety for tier-1 manufacturers in the automotive, semiconductor, and industrial sectors, ensuring you stay ahead with the latest domestic and international industry insights.

Siemens Malaysia is a leading technology company with comprehensive products and solutions for various markets in the Malaysian economy under its Digital Industries and Smart Infrastructure businesses. It focuses on the areas of intelligent infrastructure for buildings, grids, distributed energy systems, more resource-efficient factories, resilient supply chains, as well as automation and digitalization in the process and manufacturing industries. The company creates technology with purpose adding real value for customers. By combining the real and the digital worlds, Siemens empowers its customers to transform their industries and markets, helping them to transform the everyday for billions of people.

For more information, please visit www.siemens.com

Singtest Technology continues to focus on its core business of used equipment refurbishment, mainly in the diffusion process area, heating jackets, as well as RF repairs. We also work closely with China OEM partners to provide complete solutions to our customers.

Soitec, the global leader in engineered substrates, delivers high-performance Photonics-SOI (Silicon-on-Insulator) and LNOI (Lithium Niobate-on-Insulator) solutions optimized for next-generation optical innovation. Our materials provide the critical foundation for high-speed datacom and telecom, driving the power consumption and high-performance required for massive AI workloads and datacenter architectures. In addition, as a key enabler for LiDAR, biosensing, quantum and optical computing, Soitec's platform facilitates faster, energy-efficient chips that redefine connectivity.

Discover how our advanced substrates are scaling the future of optical sensing, transport, and high-performance compute.

For more information, please visit www.soitec.com

Advanced Packaging Solutions – STATS ChipPAC delivers advanced semiconductor packaging through 2.5D/3D integration, System-in-Package (SiP), wafer-level packaging, flip chip, and memory—enabling high-performance, high-density integration.

With comprehensive turnkey capabilities from package integration design through wafer bumping, assembly, final test, and global drop shipment, we support applications across automotive, computing, memory, AI edge, and power & energy, working closely with customers and ecosystem partners worldwide to deliver scalable, supply chain-ready solutions.

Learn more at www.statschippac.com

Synapse™ Si is a permanent bonding system for 300-mm wafers that supports both fusion bonding and Cu hybrid bonding. By adopting the proven designs of the platform, cleaning modules, and plasma processing modules used in front-end production, it delivers high-volume manufacturing reliability while achieving superior alignment accuracy and high throughput. In addition, productivity per unit area can be further increased by expanding bond configurations to meet customer requirements. Permanent bonding processes are expected to expand into a wide range of applications. TEL will lead the development and mass production of these new applications.